

Abstract

The invention relates to a method for applying rewiring (1) to a panel (2). For this purpose, a panel (2) is provided which has a coplanar overall upper side (16) of an upper side of a plastic compound and the upper sides of semiconductor chips (3). The method provides a rewiring layer with implementation of external contacts (8) and rewiring lines (10) which, by means of a two-stage exposure step, compensates for position errors of the semiconductor chips (3) in the component positions (4) of the panel (2).

[Figure 1]